

Semiconductor Advanced Packaging-South America Market Status and Trend Report 2013-2023

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Abstracts

Report Summary

Semiconductor Advanced Packaging-South America Market Status and Trend Report 2013-2023 offers a comprehensive analysis on Semiconductor Advanced Packaging industry, standing on the readers' perspective, delivering detailed market data and penetrating insights. No matter the client is industry insider, potential entrant or investor, the report will provides useful data and information. Key questions answered by this report include:

Whole South America and Regional Market Size of Semiconductor Advanced Packaging 2013-2017, and development forecast 2018-2023

Main market players of Semiconductor Advanced Packaging in South America, with company and product introduction, position in the Semiconductor Advanced Packaging market

Market status and development trend of Semiconductor Advanced Packaging by types and applications

Cost and profit status of Semiconductor Advanced Packaging, and marketing status

Market growth drivers and challenges

The report segments the South America Semiconductor Advanced Packaging market as:

South America Semiconductor Advanced Packaging Market: Regional Segment Analysis (Regional Consumption Volume, Consumption Volume, Revenue and Growth Rate 2013-2023):

Brazil

Argentina
Venezuela
Colombia
Others

South America Semiconductor Advanced Packaging Market: Product Type Segment Analysis (Consumption Volume, Average Price, Revenue, Market Share and Trend 2013-2023):

FO WLP
2.5D/3D
FI WLP
Flip Chip

South America Semiconductor Advanced Packaging Market: Application Segment Analysis (Consumption Volume and Market Share 2013-2023; Downstream Customers and Market Analysis)

CMOS image sensors
Wireless connectivity devices
Logic and memory devices
MEMS and sensors
Analog and mixed ICs

South America Semiconductor Advanced Packaging Market: Players Segment Analysis (Company and Product introduction, Semiconductor Advanced Packaging Sales Volume, Revenue, Price and Gross Margin):

Advanced Semiconductor Engineering
Amkor Technology
Samsung Semiconductor
TSMC
China Wafer Level CSP
ChipMOS TECHNOLOGIES
FlipChip International
HANA Micron
Interconnect Systems (Molex)
Jiangsu Changjiang Electronics Technology (JCET)

King Yuan Electronics
Tongfu Microelectronics
Nepes
Powertech Technology (PTI)
SIGNETICS
Tianshui Huatian
Ultratech
UTAC

In a word, the report provides detailed statistics and analysis on the state of the industry; and is a valuable source of guidance and direction for companies and individuals interested in the market.

Contents

CHAPTER 1 OVERVIEW OF SEMICONDUCTOR ADVANCED PACKAGING

- 1.1 Definition of Semiconductor Advanced Packaging in This Report
- 1.2 Commercial Types of Semiconductor Advanced Packaging
 - 1.2.1 FO WLP
 - 1.2.2 2.5D/3D
 - 1.2.3 FI WLP
 - 1.2.4 Flip Chip
- 1.3 Downstream Application of Semiconductor Advanced Packaging
 - 1.3.1 CMOS image sensors
 - 1.3.2 Wireless connectivity devices
 - 1.3.3 Logic and memory devices
 - 1.3.4 MEMS and sensors
 - 1.3.5 Analog and mixed ICs
- 1.4 Development History of Semiconductor Advanced Packaging
- 1.5 Market Status and Trend of Semiconductor Advanced Packaging 2013-2023
 - 1.5.1 South America Semiconductor Advanced Packaging Market Status and Trend 2013-2023
 - 1.5.2 Regional Semiconductor Advanced Packaging Market Status and Trend 2013-2023

CHAPTER 2 SOUTH AMERICA MARKET STATUS AND FORECAST BY REGIONS

- 2.1 Market Status of Semiconductor Advanced Packaging in South America 2013-2017
- 2.2 Consumption Market of Semiconductor Advanced Packaging in South America by Regions
 - 2.2.1 Consumption Volume of Semiconductor Advanced Packaging in South America by Regions
 - 2.2.2 Revenue of Semiconductor Advanced Packaging in South America by Regions
- 2.3 Market Analysis of Semiconductor Advanced Packaging in South America by Regions
 - 2.3.1 Market Analysis of Semiconductor Advanced Packaging in Brazil 2013-2017
 - 2.3.2 Market Analysis of Semiconductor Advanced Packaging in Argentina 2013-2017
 - 2.3.3 Market Analysis of Semiconductor Advanced Packaging in Venezuela 2013-2017
 - 2.3.4 Market Analysis of Semiconductor Advanced Packaging in Colombia 2013-2017
 - 2.3.5 Market Analysis of Semiconductor Advanced Packaging in Others 2013-2017
- 2.4 Market Development Forecast of Semiconductor Advanced Packaging in South

America 2018-2023

2.4.1 Market Development Forecast of Semiconductor Advanced Packaging in South America 2018-2023

2.4.2 Market Development Forecast of Semiconductor Advanced Packaging by Regions 2018-2023

CHAPTER 3 SOUTH AMERICA MARKET STATUS AND FORECAST BY TYPES

3.1 Whole South America Market Status by Types

3.1.1 Consumption Volume of Semiconductor Advanced Packaging in South America by Types

3.1.2 Revenue of Semiconductor Advanced Packaging in South America by Types

3.2 South America Market Status by Types in Major Countries

3.2.1 Market Status by Types in Brazil

3.2.2 Market Status by Types in Argentina

3.2.3 Market Status by Types in Venezuela

3.2.4 Market Status by Types in Colombia

3.2.5 Market Status by Types in Others

3.3 Market Forecast of Semiconductor Advanced Packaging in South America by Types

CHAPTER 4 SOUTH AMERICA MARKET STATUS AND FORECAST BY DOWNSTREAM INDUSTRY

4.1 Demand Volume of Semiconductor Advanced Packaging in South America by Downstream Industry

4.2 Demand Volume of Semiconductor Advanced Packaging by Downstream Industry in Major Countries

4.2.1 Demand Volume of Semiconductor Advanced Packaging by Downstream Industry in Brazil

4.2.2 Demand Volume of Semiconductor Advanced Packaging by Downstream Industry in Argentina

4.2.3 Demand Volume of Semiconductor Advanced Packaging by Downstream Industry in Venezuela

4.2.4 Demand Volume of Semiconductor Advanced Packaging by Downstream Industry in Colombia

4.2.5 Demand Volume of Semiconductor Advanced Packaging by Downstream Industry in Others

4.3 Market Forecast of Semiconductor Advanced Packaging in South America by Downstream Industry

CHAPTER 5 MARKET DRIVING FACTOR ANALYSIS OF SEMICONDUCTOR ADVANCED PACKAGING

- 5.1 South America Economy Situation and Trend Overview
- 5.2 Semiconductor Advanced Packaging Downstream Industry Situation and Trend Overview

CHAPTER 6 SEMICONDUCTOR ADVANCED PACKAGING MARKET COMPETITION STATUS BY MAJOR PLAYERS IN SOUTH AMERICA

- 6.1 Sales Volume of Semiconductor Advanced Packaging in South America by Major Players
- 6.2 Revenue of Semiconductor Advanced Packaging in South America by Major Players
- 6.3 Basic Information of Semiconductor Advanced Packaging by Major Players
 - 6.3.1 Headquarters Location and Established Time of Semiconductor Advanced Packaging Major Players
 - 6.3.2 Employees and Revenue Level of Semiconductor Advanced Packaging Major Players
- 6.4 Market Competition News and Trend
 - 6.4.1 Merger, Consolidation or Acquisition News
 - 6.4.2 Investment or Disinvestment News
 - 6.4.3 New Product Development and Launch

CHAPTER 7 SEMICONDUCTOR ADVANCED PACKAGING MAJOR MANUFACTURERS INTRODUCTION AND MARKET DATA

- 7.1 Advanced Semiconductor Engineering
 - 7.1.1 Company profile
 - 7.1.2 Representative Semiconductor Advanced Packaging Product
 - 7.1.3 Semiconductor Advanced Packaging Sales, Revenue, Price and Gross Margin of Advanced Semiconductor Engineering
- 7.2 Amkor Technology
 - 7.2.1 Company profile
 - 7.2.2 Representative Semiconductor Advanced Packaging Product
 - 7.2.3 Semiconductor Advanced Packaging Sales, Revenue, Price and Gross Margin of Amkor Technology
- 7.3 Samsung Semiconductor

- 7.3.1 Company profile
- 7.3.2 Representative Semiconductor Advanced Packaging Product
- 7.3.3 Semiconductor Advanced Packaging Sales, Revenue, Price and Gross Margin of Samsung Semiconductor
- 7.4 TSMC
 - 7.4.1 Company profile
 - 7.4.2 Representative Semiconductor Advanced Packaging Product
 - 7.4.3 Semiconductor Advanced Packaging Sales, Revenue, Price and Gross Margin of TSMC
- 7.5 China Wafer Level CSP
 - 7.5.1 Company profile
 - 7.5.2 Representative Semiconductor Advanced Packaging Product
 - 7.5.3 Semiconductor Advanced Packaging Sales, Revenue, Price and Gross Margin of China Wafer Level CSP
- 7.6 ChipMOS TECHNOLOGIES
 - 7.6.1 Company profile
 - 7.6.2 Representative Semiconductor Advanced Packaging Product
 - 7.6.3 Semiconductor Advanced Packaging Sales, Revenue, Price and Gross Margin of ChipMOS TECHNOLOGIES
- 7.7 FlipChip International
 - 7.7.1 Company profile
 - 7.7.2 Representative Semiconductor Advanced Packaging Product
 - 7.7.3 Semiconductor Advanced Packaging Sales, Revenue, Price and Gross Margin of FlipChip International
- 7.8 HANA Micron
 - 7.8.1 Company profile
 - 7.8.2 Representative Semiconductor Advanced Packaging Product
 - 7.8.3 Semiconductor Advanced Packaging Sales, Revenue, Price and Gross Margin of HANA Micron
- 7.9 Interconnect Systems (Molex)
 - 7.9.1 Company profile
 - 7.9.2 Representative Semiconductor Advanced Packaging Product
 - 7.9.3 Semiconductor Advanced Packaging Sales, Revenue, Price and Gross Margin of Interconnect Systems (Molex)
- 7.10 Jiangsu Changjiang Electronics Technology (JCET)
 - 7.10.1 Company profile
 - 7.10.2 Representative Semiconductor Advanced Packaging Product
 - 7.10.3 Semiconductor Advanced Packaging Sales, Revenue, Price and Gross Margin of Jiangsu Changjiang Electronics Technology (JCET)

7.11 King Yuan Electronics

7.11.1 Company profile

7.11.2 Representative Semiconductor Advanced Packaging Product

7.11.3 Semiconductor Advanced Packaging Sales, Revenue, Price and Gross Margin of King Yuan Electronics

7.12 Tongfu Microelectronics

7.12.1 Company profile

7.12.2 Representative Semiconductor Advanced Packaging Product

7.12.3 Semiconductor Advanced Packaging Sales, Revenue, Price and Gross Margin of Tongfu Microelectronics

7.13 Nepes

7.13.1 Company profile

7.13.2 Representative Semiconductor Advanced Packaging Product

7.13.3 Semiconductor Advanced Packaging Sales, Revenue, Price and Gross Margin of Nepes

7.14 Powertech Technology (PTI)

7.14.1 Company profile

7.14.2 Representative Semiconductor Advanced Packaging Product

7.14.3 Semiconductor Advanced Packaging Sales, Revenue, Price and Gross Margin of Powertech Technology (PTI)

7.15 SIGNETICS

7.15.1 Company profile

7.15.2 Representative Semiconductor Advanced Packaging Product

7.15.3 Semiconductor Advanced Packaging Sales, Revenue, Price and Gross Margin of SIGNETICS

7.16 Tianshui Huatian

7.17 Ultratech

7.18 UTAC

CHAPTER 8 UPSTREAM AND DOWNSTREAM MARKET ANALYSIS OF SEMICONDUCTOR ADVANCED PACKAGING

8.1 Industry Chain of Semiconductor Advanced Packaging

8.2 Upstream Market and Representative Companies Analysis

8.3 Downstream Market and Representative Companies Analysis

CHAPTER 9 COST AND GROSS MARGIN ANALYSIS OF SEMICONDUCTOR ADVANCED PACKAGING

- 9.1 Cost Structure Analysis of Semiconductor Advanced Packaging
- 9.2 Raw Materials Cost Analysis of Semiconductor Advanced Packaging
- 9.3 Labor Cost Analysis of Semiconductor Advanced Packaging
- 9.4 Manufacturing Expenses Analysis of Semiconductor Advanced Packaging

CHAPTER 10 MARKETING STATUS ANALYSIS OF SEMICONDUCTOR ADVANCED PACKAGING

- 10.1 Marketing Channel
 - 10.1.1 Direct Marketing
 - 10.1.2 Indirect Marketing
 - 10.1.3 Marketing Channel Development Trend
- 10.2 Market Positioning
 - 10.2.1 Pricing Strategy
 - 10.2.2 Brand Strategy
 - 10.2.3 Target Client
- 10.3 Distributors/Traders List

CHAPTER 11 REPORT CONCLUSION

CHAPTER 12 RESEARCH METHODOLOGY AND REFERENCE

- 12.1 Methodology/Research Approach
 - 12.1.1 Research Programs/Design
 - 12.1.2 Market Size Estimation
 - 12.1.3 Market Breakdown and Data Triangulation
- 12.2 Data Source
 - 12.2.1 Secondary Sources
 - 12.2.2 Primary Sources
- 12.3 Reference

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